

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

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PCN #: A1402-03 DATE 5-Mar-2014 Product Affected: 21.0mm x 21.0mm FCBGA-399 27.0mm x 27.0mm FCBGA-675 Refer to Attachment II for the affected part numbers		MEANS OF DISTII □ Product Mark □ Back Mark □ Date Code ■ Other	Assembly lot marked on the device provides traceability to the material used			
Date Effective: 4-Jun-2014						
Contact: IDT PCN DESK		Attachment:	Yes No			
E-mail: pcndesk@idt.com		Samples: Please contact your local sales representative for sample request & availability.				
DESCRIPTION AND PURPOSE OF CHA	NGE:					
Die Technology Wafer Fabrication Process Assembly Process Equipment Material This notification is to advise our customers that the underfill material will be changed from UA03 to UA32. There is no change to the moisture performance.						
☐ Testing ☐ Manufacturing Site ☐ Data Sheet ☐ Other	Attachment I details t Attachment II shows					
RELIABILITY/QUALIFICATION SUMMARY: Refer to qualification data shown in attachment I.						
CUSTOMER ACKNOWLEDGMENT OF	RECEIPT:					
IDT records indicate that you require writter to grant approval or request additional informit will be assumed that this change is accepta IDT reserves the right to ship either version on the earlier version has been depleted.	n notification of this cha mation. If IDT does not able.	t receive acknowledge	ement within 30 days of this notice			
Customer:	□	Approval for	shipments prior to effective date.			
Name/Date:	E-	Mail Address:				
Title:	Ph	one# /Fax# :				
CUSTOMER COMMENTS:						
IDT ACKNOWLEDGMENT OF RECEIR	T:					
RECD. BY:		DATE:				

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ATTACHMENT I - PCN #: A1402-03

PCN Type: Change of Materials

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that the underfill material will be changed from UA03 to UA32.

There is no change to the moisture performance of these packages.

Change of Material Sets

Package	From	То	
FCBGA-399	Underfill: UA03	UA32	
FCBGA-675	Undermi: UA03		

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ATTACHMENT I - PCN #: A1402-03

Qualification Test Plans and Results:

Qual Plan & Results: The qualification was performed in accordance with JEDEC47 recommended tests.

Qual Vehicle: 27.0mm x 27.0mm FCBGA-675 (3 lots)

		Test Re	esults (S	S / Rej)
Test Description	Test Method	Lot 1	Lot 2	Lot 3
* HAST - unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	25/0	25/0	25/0
* Temperature Humidity Biased (85 °C/85% RH, 1000 Hrs)	JESD22-A101	25/0	25/0	25/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	25/0	25/0	25/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	25/0	25/0	25/0
Solder Ball Shear Test (1000 Hrs)	JESD22-B117	5/0	5/0	5/0
X-ray Examination	IDT Spec MAC-3012	45/0	45/0	45/0

Note:

^{*} Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test

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ATTACHMENT II - PCN #: A1402-03

Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
TSI576-10GCLY	TSI578-10GCL	TSI578-10GIL	TSI578A-10GIL
TSI576-10GILY	TSI578-10GCLY	TSI578-10GILY	TSI578A-10GILY